100% Material Declaration Data Sheet PDG8

Average Weight: 0.528 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.006650**	**1.26%**
	Silicon	7440-21-3	100.00		0.006653	
Die Attach Material					**0.001980**	**0.37%**
	Resin	Trade Secret	21.00		0.000415	
	Silver	7440-22-4	70.00		0.001383	
	Metal Oxide	Trade Secret	3.00		0.000059	
	Amine	Trade Secret	3.00		0.000059	
	Gamma Butyrolactone	Trade Secret	3.00		0.000059	
Mold Compound					**0.318240**	**60.31%**
	Resin Type Ortho Cresol Novolac	Trade Secret	13.50		0.042962	
	SiO2	60676-86-0	86.50		0.275278	
Leadframe					**0.189840**	**35.98%**
	Copper	7440-50-8	97.50		0.185099	
	Iron	7439-89-6	2.35		0.004461	
	Phosphorus	7723-14-0	0.03		0.000057	
	Zinc	7440-66-6	0.12		0.000228	
Leadframe Plating					**0.001350**	**0.26%**
	Silver	7440-22-4	100.00		0.001350	
Bond Wire					**0.000410**	**0.08%**
	Gold	7440-57-5	100.00		0.000414	
Ext. Plating					**0.009160**	**1.74%**
	Tin	7440-31-5	100.00		0.009164	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.
11/12/06	1.3	New epoxy mold compound composition